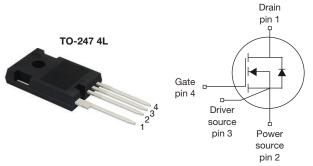


# MaxSiC<sup>™</sup> 1200 V N-Channel SiC MOSFET



Marking Code: 120A250FL

PRODUCT SUMMARY					
V <sub>DS</sub> (V) at T <sub>J</sub> max.	12	1200			
R <sub>DS(on)</sub> typ. (mΩ) at 25 °C	V <sub>GS</sub> = 20 V	250			
Q <sub>g</sub> typ. (nC)	20				
I <sub>D</sub> (A)	10.5				
C <sub>oss</sub> (pF)	21.2				
P <sub>D</sub> (W)	56				
Configuration	Single				

#### **FEATURES**

- · Fast switching speed
- Short circuit withstand time 3 µs

 Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



#### **APPLICATIONS**

- Charger
- Industrial UPS
- · Boost inverter
- DC/DC converter

ORDERING INFORMATION	
Package	TO-247 4L
Lead (Pb)-free and halogen-free	MXP120A250FL-Y-GE3

ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °	C, unless otherwis	se noted)		
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage <sup>a</sup>		$V_{DS}$	1200	V
Gate-source voltage		$V_{GS}$	-10 / +22	
Continuous drain current	T <sub>C</sub> = 25 °C	I <sub>D</sub>	10.5	А
	T <sub>C</sub> = 100 °C	I <sub>D</sub>	6.7	
Pulsed drain current <sup>b</sup>		I <sub>DM</sub>	21	
Short-circuit withstand time		T <sub>SC</sub>	3	μs
Maximum power dissipation	T <sub>C</sub> = 25 °C	$P_{D}$	56	W
	T <sub>C</sub> = 100 °C	$P_{D}$	22	
Operating junction and storage temperature range	·	T <sub>J</sub> , T <sub>stq</sub>	-55 to +150	°C

#### Notes

- a.  $T_J = 25$  °C to 150 °C
- b. Repetitive rating; pulse width limited by maximum junction temperature

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R <sub>thJA</sub>	-	40	°C/W	
Maximum junction-to-case (drain)	R <sub>thJC</sub>	-	2.24	C/ VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub>	1200	-	-	V	
Onto a surrent brunch and unabtered (All)		$V_{DS} = V_{GS}$ , $I_D = 10 \text{ mA}$		-	3.1	-	V
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$	I <sub>D</sub> = 10 mA, T <sub>J</sub> = 150 °C	-	2.3	-	V
Gate-source leakage	lasa	V <sub>GS</sub> =	$V_{GS} = +22 \text{ V}, V_{DS} = 0 \text{ V}$ $V_{GS} = -10 \text{ V}, V_{DS} = 0 \text{ V}$		-	100	nA
Gate-Source leakage	I <sub>GSS</sub>	V <sub>GS</sub> =			-	-100	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =	V <sub>DS</sub> = 960 V, V <sub>GS</sub> = 0 V		-	10	μΑ
Drain-source on-state resistance		V <sub>GS</sub>	V <sub>GS</sub> = 20 V, I <sub>D</sub> = 4 A		250	313	
	Б	V <sub>GS</sub> = 20 \	V <sub>GS</sub> = 20 V, I <sub>D</sub> = 4 A, T <sub>J</sub> = 150 °C		380	475	- mΩ
	R <sub>DS(on)</sub>	V <sub>GS</sub>	V <sub>GS</sub> = 18 V, I <sub>D</sub> = 4 A		287	359	
		V <sub>GS</sub> = 18 \	V <sub>GS</sub> = 18 V, I <sub>D</sub> = 4 A, T <sub>J</sub> = 150 °C		395	494	
Dynamic							
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 V$ ,		-	447	-	pF
Output capacitance	C <sub>oss</sub>	] ,	V <sub>DS</sub> = 800 V, f = 1 MHz		21.2	-	
Reverse transfer capacitance	C <sub>rss</sub>				3.2	-	
Total gate charge	Qg		V <sub>GS</sub> = 18 V I <sub>D</sub> = 4 A, V <sub>DS</sub> = 800 V	-	20.3	-	nC
Gate-source charge	$Q_{gs}$	V <sub>GS</sub> = 18 V		-	5.5	-	
Gate-drain charge	$Q_{gd}$				7.9	-	1 !
Gate Resistance	$R_g$	V <sub>DS</sub> = 0 V, f = 1 MHz		-	34	-	Ω
Switching Characteristics							
Turn-on delay time	t <sub>d(on)</sub>				8.5	-	ns ns
Rise time	t <sub>r</sub>				11.5	-	
Turn-off delay time	t <sub>d(off)</sub>	$V_{GS}$ = -5 V ~ 18 V, $I_D$ = 4 A, $V_{DS}$ = 800 V, $R_{g(ext)}$ = 4.4 $\Omega$		-	8.5	-	
Fall time	t <sub>f</sub>			-	14.5	-	
Turn-on switching energy	E <sub>on</sub>			-	67	-	1
Turn-off switching energy	E <sub>off</sub>			-	5	-	μJ
Reverse Diode Characteristics							
Reverse recovery time	t <sub>rr</sub>	$V_{GS} = -5 \text{ V, } I_{SD} = 4 \text{ A,}$ $V_{R} = 800 \text{ V,}$ $di/dt = 1000 \text{ A/}\mu\text{s}$		-	7.5	-	ns
Reverse recovery charge	Q <sub>rr</sub>			-	12	-	nC
Reverse recovery current	I <sub>rrm</sub>			-	2.8	-	Α

#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

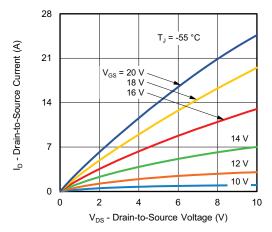


Fig. 1 - Typical Output Characteristics

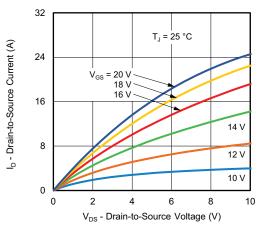


Fig. 2 - Typical Output Characteristics

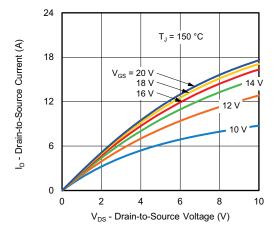


Fig. 3 - Typical Output Characteristics

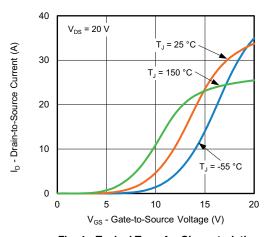


Fig. 4 - Typical Transfer Characteristics

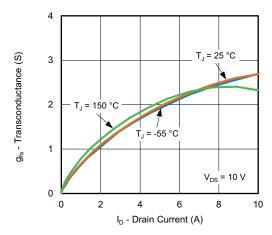


Fig. 5 - Forward Transconductance vs. Drain Current

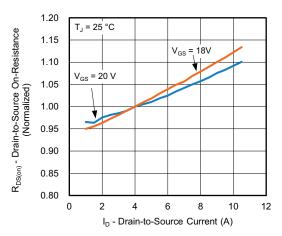


Fig. 6 - Normalized On-Resistance vs. Drain-to-Source Current



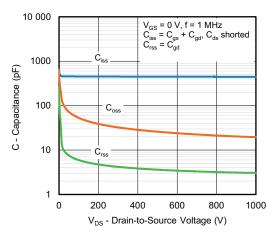


Fig. 7 - Typical Capacitance vs. Drain-to-Source Voltage

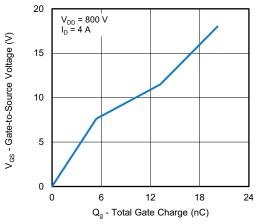


Fig. 8 - Typical Gate Charge vs. Gate-to-Source Voltage

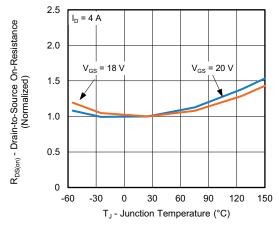


Fig. 9 - Normalized On-Resistance vs. Temperature

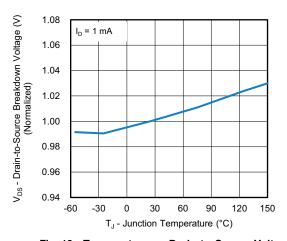


Fig. 10 - Temperature vs. Drain-to-Source Voltage

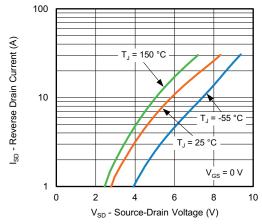


Fig. 11 - Typical Source-Drain Diode Forward Voltage

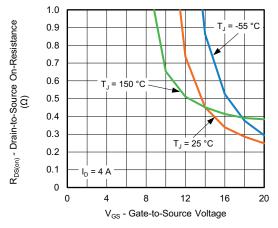


Fig. 12 - On-Resistance vs. Gate-to-Source Voltage



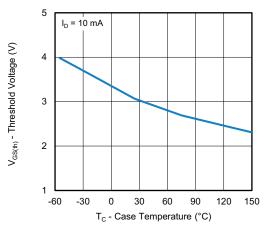


Fig. 13 - Threshold Voltage vs. Case Temperature

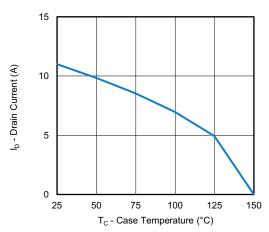


Fig. 14 - Drain Current vs. Case Temperature

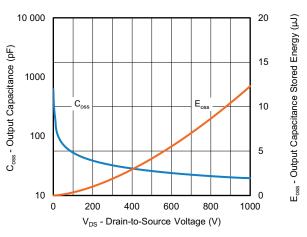


Fig. 15 - Output Capacitance and its Stored Energy vs. Drain-to-Source Voltage

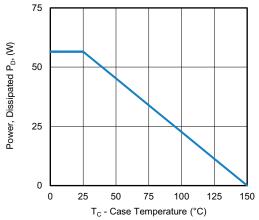


Fig. 16 - Power, Dissipated P<sub>D</sub> vs. Case Temperature

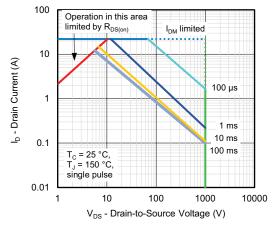


Fig. 17 - Safe Operating Area

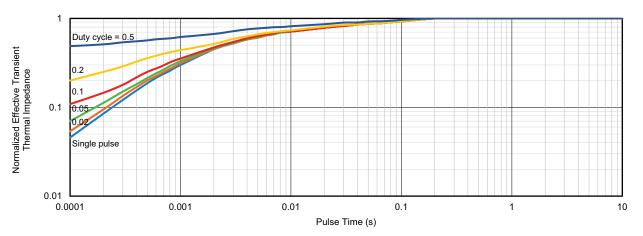


Fig. 18 - Normalized Effective Transient Thermal Impedance



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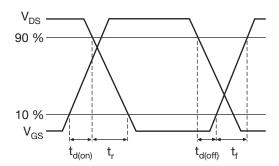


Fig. 19 - Waveforms of Switching Time

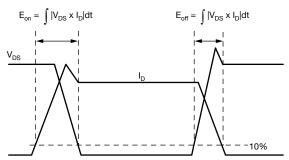


Fig. 20 - Waveforms for Switching Energy

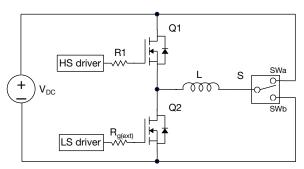


Fig. 21 - Switching and Reverse Diode Characteristics Measurement Circuit

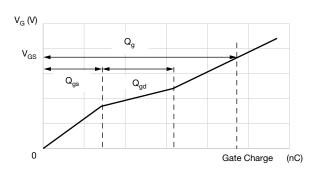


Fig. 22 - Waveforms for Gate Charge

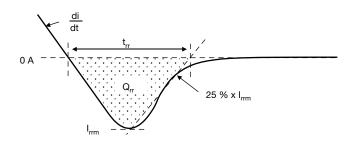


Fig. 23 - Waveforms for Reverse Recovery

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